General Notes:
All dimensions are in mils (0.001") unless otherwise specified.
Tolerance on all dimensions shall be ±0.005" unless otherwise specified.

Assembly Notes:
1. Assemble board per IPC A-610C Class I.
2. RoHS compliant, Lead-Free solder process required.
3. Assembly should be flux and residue free
4. Inspect J100 for proper solder flow around through hole pins
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